

DT1042-04SO

### 4 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY

### **Features**

- Low Clamping Voltage, I/O to V<sub>SS</sub>
- Typical 9V at 10A 100ns, TLP
- Typical 7.7V at 6A 8µs/20µs
- IEC 61000-4-2 (ESD): Air +27/-19kV, Contact ±16kV
- IEC 61000-4-4 (EFT): Level-4
- IEC 61000-4-5 (Lightning): ±6A
- 4 Channels of ESD protection
- Low Channel Input Capacitance of 0.65pF Typical
- TLP Dynamic Resistance: 0.25Ω
- Typically Used for High Speed Ports such as USB 2.0, IEEE1394, HDMI, Laptop and Personal Computers, Flat Panel Displays, Video Graphics Displays, SIM Ports
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

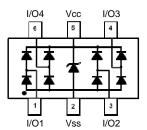
## **Mechanical Data**

- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Copper leadframe
- (Lead Free Plating). Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.016 grams (approximate)

SOT26



Top View



Device Schematic

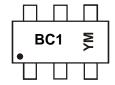
### **Ordering Information** (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DT1042-04SO-7	Standard	BC1	7	8	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## **Marking Information**



BC1 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Year	20	13	20	14	20	15	20	16	20	17	20	18
Code	ļ ,	4	Е	3	(			)	Е		F	=
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current, per IEC 61000-4-5	I <sub>PP_I/O</sub>	±6	Α	I/O to V <sub>SS</sub> , 8/20 μs
Peak Pulse Power, per IEC 61000-4-5	P <sub>PP_I/O</sub>	55	W	I/O to V <sub>SS</sub> , 8/20 µs
Operating Voltage (DC)	V <sub>DC</sub>	5.5	V	I/O to V <sub>SS</sub>
ESD Protection – Contact Discharge, per IEC 61000-4-2	V <sub>ESD_I/O</sub>	±16	kV	I/O to V <sub>SS</sub>
ESD Protection – Air Discharge, per IEC 61000-4-2	V <sub>ESD_I/O</sub>	+27/-19	kV	I/O to V <sub>SS</sub>
Operating Temperature	T <sub>OP</sub>	-55 to +85	°C	_
Storage Temperature	T <sub>STG</sub>	-55 to +150	°C	_

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit	
Power Dissipation Typical (Note 5)	P <sub>D</sub>	300	mW	
Thermal Resistance, Junction to Ambient Typical (Note 5)	$R_{\theta JA}$	417	°C/W	

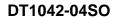
## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Working Voltage	VRWM		—	5.0	V	V <sub>CC</sub> to V <sub>SS</sub>
Reverse Current (Note 6)	I <sub>R(Vcc to Vss)</sub>		_	1.0	μA	$V_R = V_{RWM} = 5V$ , $V_{CC}$ to $V_{SS}$
Reverse Current (Note 6)	I <sub>R(IO to Vss)</sub>		_	0.5	μA	V <sub>R</sub> = V <sub>RWM</sub> = 5V, any I/O to V <sub>SS</sub>
Reverse Breakdown Voltage	V <sub>BR</sub>	6.2	_		V	I <sub>R</sub> = 1mA, V <sub>CC</sub> to V <sub>SS</sub>
Forward Clamping Voltage	V <sub>F</sub>	-1.0	-0.8		V	I <sub>F</sub> = -15mA, V <sub>CC</sub> to V <sub>SS</sub>
Daviana Classia a Valta a (Nata 7)	V <sub>C_Vcc</sub>		6.3	_	V	I <sub>PP</sub> = 9A, V <sub>CC</sub> to V <sub>SS</sub> , 8/20 μs
Reverse Clamping Voltage(Note 7)	V <sub>C_I/O</sub>	_	7.7	9	V	I <sub>PP</sub> = 6A, I/O to V <sub>SS</sub> , 8/20 μs
ECD Classain a Valta as	V <sub>ESD_Vcc</sub>		6.8	_	V	TLP, 10A, tp = 100 ns, $V_{CC}$ to $V_{SS}$ , per Fig. 8
ESD Clamping Voltage	V <sub>ESD_I/O</sub>	_	9		V	TLP, 10A, tp = 100 ns, I/O to V <sub>SS</sub> , per Fig. 8
D	R <sub>DIF_Vcc</sub>	_	0.1	_	Ω	TLP, 10A, tp = 100 ns, V <sub>CC</sub> to V <sub>SS</sub>
Dynamic Resistance	R <sub>DIF_I/O</sub>		0.25		Ω	TLP, 10A, tp = 100 ns, I/O to V <sub>SS</sub>
Channel Input Capacitance	C <sub>I/O to</sub> V <sub>SS</sub>	_	0.65	0.8	pF	V <sub>R</sub> = 2.5V, V <sub>CC</sub> = 5V, f = 1MHz
Variation of Channel Input Capacitance	$\Delta C_{I/O}$	_	0.02		pF	V <sub>CC</sub> = 5V, V <sub>SS</sub> = 0V, I/O = 2.5V, f =1MHz, T=+25°C, I/O_x to V <sub>SS</sub> - I/O_y to V <sub>SS</sub>

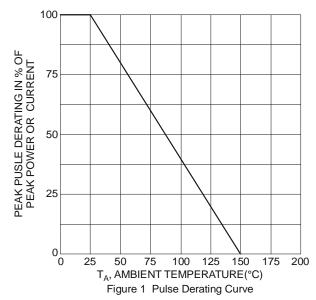
Notes:

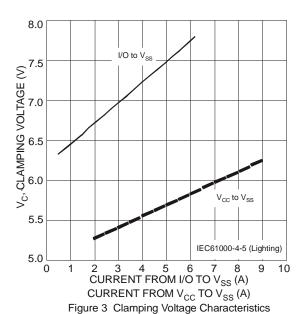
- 5. Device mounted on Polymide PCB pad layout (2oz copper) as shown on Diodes Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.

  6. Short duration pulse test used to minimize self-heating effect.
- 7. Clamping voltage value is based on an 8x20µs peak pulse current (Ipp) waveform.









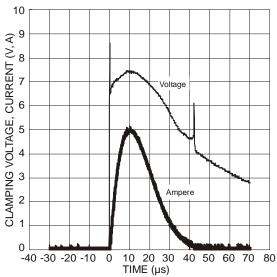


Figure 5 Waveform of Clamping Voltage, Current vs. Time (8/20µs, I/O to V<sub>SS</sub>)

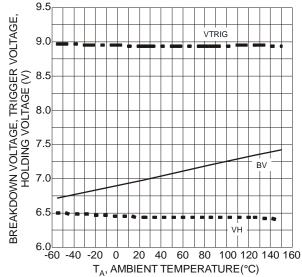
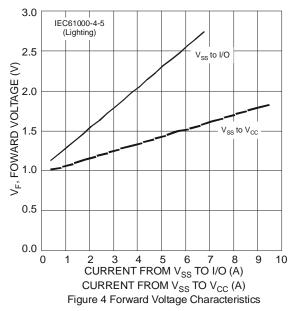


Figure 2 Breakdown Voltage, Trigger Voltage, Holding Voltage vs. Ambient Temperature



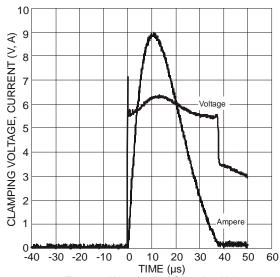
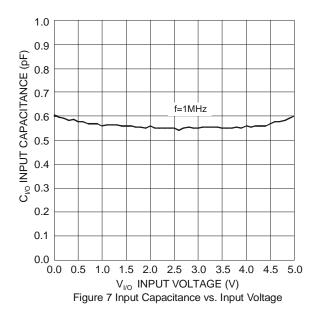
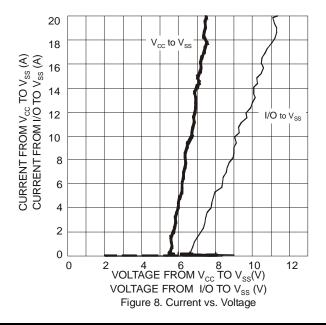


Figure 6 Waveform of Clamping Voltage, Current vs. Time (8/20 $\mu$ s, V<sub>CC</sub> to V<sub>SS</sub>)

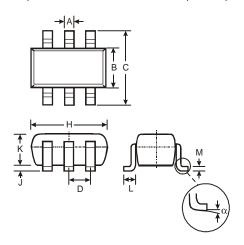






# **Package Outline Dimensions**

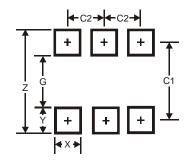
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT26							
Dim	Min	Max	Тур				
Α	0.35	0.50	0.38				
В	1.50	1.70	1.60				
С	2.70	3.00	2.80				
D	_		0.95				
Н	2.90	3.10	3.00				
J	0.013	0.10	0.05				
K	1.00	1.30	1.10				
L	0.35	0.55	0.40				
М	0.10	0.20	0.15				
α	0°	8°	_				
All Dimensions in mm							

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	3.20
G	1.60
Х	0.55
Υ	0.80
C1	2.40
C2	0.95



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